



Compatible with Lead and Lead-Free Solders

MG Chemicals soldering flux provides high tack-force and superior wetting for both leaded and non-leaded solder alloys. The flux comes in both liquid and paste formats, and in Rosin Activated (RA), No Clean (NC) and Water Soluble (WS) flux chemistries. Our fluxes provide exceptional adhesion to copper, and form an effective barrier against oxidation of circuit traces.

Features & Benefits

- No-clean options available
- Meets J-STD-004B
- RoHS compliant
- Available as liquid or paste

Applications

- General purpose soldering of PCBs, wire, cable, and semiconductors
- Repair and rework
- Through-hole and surface mount
- Solder touch-ups

Liquid Flux

835 — Rosin-based flux

8351 — No-clean, halogen-free flux

836LFNC — Lead-free, no-clean flux

837LFWS — Lead-free, water soluble flux

Paste Flux

8341 — No-clean, halogen-free flux

8342 — Rosin-based flux

Soldering Flux



	LIQUID FLUX				PASTE FLUX	
	835	8351	836LFNC	837LFWS	8341	8342
PROPERTIES						
Flux Classification	ROM1	ORL0	ORL0	ORH1	ROL1	RA
Flux Type	Rosin	Organic	Organic	Organic	Rosin	Rosin
Flux Activity	Moderate	Low	Low	High	Low	Moderate
Copper Mirror	Partial removal	Pass	Pass	Removal	Pass	—
Corrosion Test	Pass	—	—	Pass	Pass	—
Acid Number (mgKOH/g sample)	—	14–16	14–16	—	126	—
Halides (by weight)	0.44%	<0.5%	<0.5%	2.2%	<0.5%	—
Surface Insulation Resistance (SIR)	—	2.1 x 10 ⁹ Ω	2.1 x 10 ⁹ Ω	1.8 x 10 ¹⁰ Ω	—	—
Cleaning Requirements	Recommended	Not required	Not required	Recommended	Not required	Required
AVAILABLE PACKAGING						
Net contents	835-100ML 835-100MLCA 835-1L	8351-125ML 8351-1L 8351-4L 8351-20L	836LFNC-1L	837LFWS-1L	8341-10ML 8341-50ML	8342-50G

